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Title: **JP63143814A2: OPTICAL HEATING APPARATUS**

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Country: JP Japan
Kind: A

Inventor(s): **WATANABE TETSUO**
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Applicant/Assignee: **HITACHI LTD**



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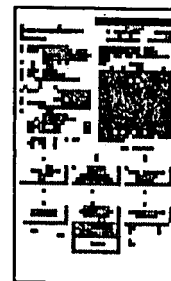
Issued/Filed Dates: **June 16, 1988 / Dec. 8, 1986**

Application **JP1986000290413**

Number:

IPC Class: **H01L 21/26;**

► Interested in classification by use rather than just by description?



Priority Number(s): Dec. 8, 1986 **JP1986000290413**

Abstract: **Purpose:** To compensate temperature decrease caused in the peripheral region of a wafer by radiation of secondary radiant heat from an auxiliary heating means and to enable the wafer to be heated uniformly all over the surface thereof, particularly under steady temperature condition, by providing an auxiliary heating means performing temperature compensation for an object to be treated disposed within a treating space by means of its secondary radiant heat.



Constitution: An auxiliary heating plate 11 is mounted between a wafer 4 supported by a support pin 10 and a holder body 8a, such that the plate 11 is in parallel and coaxial with the wafer 4. Since light beams from a group of halogen lamps 3 disposed below the wafer 4 are intercepted by the auxiliary heating plate 11, the wafer 4 is not heated so well as in the case that no auxiliary plate 11 is present. However, the heating effect is increased locally at the peripheral region of the wafer 4 by the radiation of secondary radiant heat from the peripheral region of the auxiliary plate 11 having a larger diameter than that of the wafer. Accordingly, the wafer 4 has temperature characteristics as represented by the curve C in the drawing. Thus, temperature decrease in the peripheral region of the wafer 4 can be compensated and uniform temperature characteristics can be obtained approximately all over the wafer 4.